

RoHS Compliant Product
 A suffix of "-C" specifies halogen and lead-free

DESCRIPTION

These miniature surface mount MOSFETs utilize High Cell Density trench process to provide low R_{DS(on)} and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

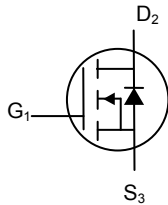
TYPICAL APPLICATIONS

- Low R_{DS(on)} Provides Higher Efficiency and Extends Battery Life.
- Low Thermal impedance copper leadframe TO-220P saves board space.
- Fast Switch speed.
- High performance trench technology.

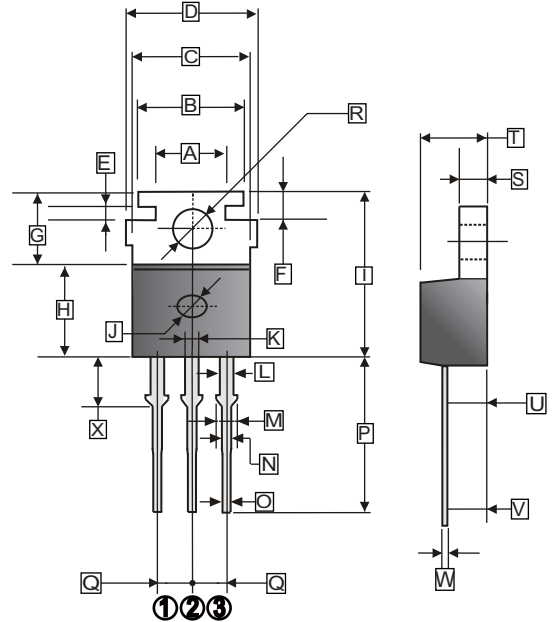
PRODUCT SUMMARY

SSE90N06-30P		
V _{DS} (V)	R _{DS(on)} (mΩ)	I _D (A)
60	26.5@V _{GS} = 10V	87 ¹
	32.5@V _{GS} = 4.5V	

N-Channel



TO-220P



Dimensions in millimeters

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	7.90	8.10	N	0.75	0.95
B	9.45	9.65	O	0.66	0.86
C	9.87	10.47	P	13.50	14.50
D	-	11.50	Q	2.44	3.44
E	1.06	1.46	R	3.50	3.70
F	2.60	3.00	S	1.15	1.45
G	6.30	6.70	T	4.30	4.70
H	8.35	8.75	U	-	2.7
J	1.60	Typ.	V	1.89	3.09
K	1.10	1.30	W	0.40	0.60
L	1.17	1.37	X	2.60	3.60
M	-	1.50			

ABSOLUTE MAXIMUM RATINGS(T_A=25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Ratings	Unit
		Maximum	
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹	I _D	87	A
Pulsed Drain Current ²	I _{DM}	240	A
Continuous Source Current (Diode Conduction) ¹	I _S	90	A
Power Dissipation ¹	P _D	300	W
Operating Junction and Storage Temperature Range	T _j , T _{stg}	-55 ~ 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Unit
Maximum Junction to Ambient ¹	R _{θJA}	62.5	°C / W
Maximum Junction to Case	R _{θJC}	0.5	

Notes

- 1 Package Limited.
- 2 Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Gate-Threshold Voltage	$V_{GS(th)}$	1	-	-	V	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$
Gate-Body Leakage	I_{GSS}	-	-	± 100	nA	$V_{DS}=0\text{V}$, $V_{GS}=20\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1	uA	$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$
		-	-	25		$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$
On-State Drain Current ¹	$I_{D(on)}$	120	-	-	A	$V_{DS}=5\text{V}$, $V_{GS}=10\text{V}$
Drain-Source On-Resistance ¹	$R_{DS(ON)}$	-	-	26.5	m Ω	$V_{GS}=10\text{V}$, $I_D=30\text{A}$
		-	-	32.5		$V_{GS}=4.5\text{V}$, $I_D=20\text{A}$
Forward Transconductance ¹	g_{fs}	-	30	-	S	$V_{DS}=15\text{V}$, $I_D=30\text{A}$
Diode Forward Voltage	V_{SD}	-	1.1	-	V	$I_S=34\text{A}$, $V_{GS}=0\text{V}$
DYNAMIC ²						
Total Gate Charge	Q_g	-	8.5	-	nC	$V_{DS}=15\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=90\text{A}$
Gate-Source Charge	Q_{gs}	-	3.3	-		
Gate-Drain Charge	Q_{gd}	-	4.0	-		
Turn-on Delay Time	$T_{d(on)}$	-	18	-	nS	$V_{DD}=25\text{V}$, $V_{GEN}=10\text{V}$, $R_L=25\Omega$, $I_D=34\text{A}$
Rise Time	T_r	-	59	-		
Turn-off Delay Time	$T_{d(off)}$	-	37	-		
Fall Time	T_f	-	9	-		

Notes

- 1 Pulse test : $PW \leq 300 \mu\text{s}$ duty cycle $\leq 2\%$.
- 2 Guaranteed by design, not subject to production testing.